

Glass Paste for MEMS Sealing 5290D

This is the glass paste for MEMS mounting. (lead-based)

●Characteristics

This is available for mounting between low-expansion substrates like silicon wafer and glass s

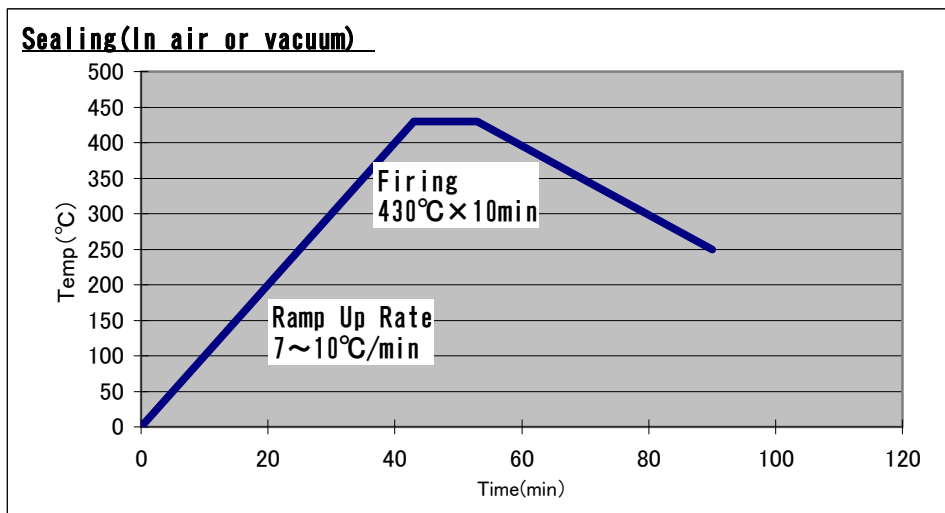
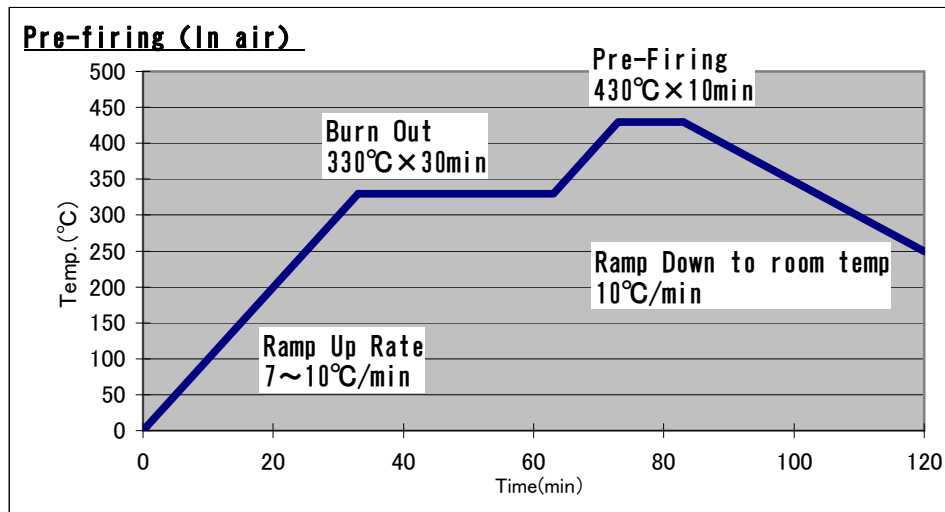
●Property

Glass Characteristics	Glass Type	Thermal Expansion ($\times 10^{-7}/^{\circ}\text{C}$)	Transformation Point ($^{\circ}\text{C}$)	Softening Point ($^{\circ}\text{C}$)	lead
Devitrifying	$\text{SiO}_2 \cdot \text{B}_2\text{O}_3 \cdot \text{PbO}$	79	340	405	containing

●Recommended Use Conditions

Dry Conditions Drying Temperature 120°C
Drying Time 10minutes

Recommended Firing Profile



※ Product information is subject to alternation without notice.